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Advanced Quality Planning (AQP) Matrix

Form (Spreadsheet)

Revision: 91

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Manufacturing/Operations Requirements Advanced Quality Planning (AQP) Matrix

Document Number: 913-3592   **Revision: 91**

Determine requirements by selecting the column that best fits commodity or supplier type ▶

Revision: 91

Column key (Supplier Type Columns):

Letter	Supplier Type
A	EM — Boards, Assemblies & Systems
B	JDM — Boards, Assemblies & Systems
C	ODM — Boards, Assemblies & Systems
D	OEM — Boards, Assemblies & Systems
E	Power
F	General
G	HDD, SDD — Drives
H	OEM Tape — Drives
I	Reman
J	HBAs, Switches, NICs
K	Tape Media
L	Memory
M	PCB Fab
P	ASIC / ASSP
Q	Optical/Optoelectronics
R	Point of Sales/Hospitality
S	Distributor
T	Hub
U	JDM - T1

Process	Category	Doc. Number	Document Title	A	B	C	D	E	F	G	H	I	J	K	L	M	P	Q	R	S	T	U
— **Sustaining, Traceability and Corporate Documents**																						
Design of Product, Process, and Tooling	Tooling	923-3404-xx	Oracle Sheetmetal and Plastic Tooling Requirements Specification and Guidelines	X				X										X				X
Design of Product, Process, and Tooling	Tooling	913-3565-xx	Oracle Plastic Tool Specification Form	X				X										X				X
Design of Product, Process, and Tooling	Tooling	913-3566-xx	Oracle Sheetmetal Tool Specification Form	X				X										X				X
Design of Product, Process, and Tooling	PCBA DF*	923-3664-xx	External Manufacturer (EM) Printed Circuit Board Assembly (PCBA) Design for (DF*) Requirements	X	X																	X
Design of Product, Process, and Tooling	PCB (DFT)	7336429	In-Circuit Test (ICT) Design for Testability	X	X	X	X															X
Product, Tooling and Factory Qualification	Air Quality	923-7051939-xx	Oracle Environmental Controls - Factory Qualification and Maintenance	X	X	X																X
Product, Tooling and Factory Qualification	FAI	923-2320-xx	Storage Device First Article Inspection (FAI) Guidelines							X	X		X									
Product, Tooling and Factory Qualification	FAI	923-3763-xx	Packaging First Article Inspection Reporting (FAIR)	X	X	X			X				X	X				X	X			X
Product, Tooling and Factory Qualification	FAI	923-3757	Memory DIMM Kit First Article Generation Specification for External Manufacturers (EMs)	X			X		X									X				X
Product, Tooling and Factory Qualification	FAI	AQP-10028	Oracle L11 Functional FAI General Requirements	X																		
Product, Tooling and Factory Qualification	HDD	923-1336-xx	Storage Device Supplier Certification Process							X												
Product, Tooling and Factory Qualification	Qual	923-3577-xx	Qualification Management Process	X														X				X
Product, Tooling and Factory Qualification	RQT	913-3572-xx	Reliability Qualification Test (RQT) Planning, Monitoring, and Reporting Template	X		X																X
Product, Tooling and Factory Qualification	Tooling	923-3402-xx	Mechanical Part and Sub-Assembly Qualification and Approval Process	X			X	X										X				X
Product, Tooling and Factory Qualification	Qual	923-7333578	Production Release Criteria for Custom Power Supply Units (PSU)					X														
Product, Tooling and Factory Qualification	Qual	7091106	PCBA Qualification Procedure for PCB Laminate													X						
Product, Tooling and Factory Qualification	Qual	7092461	Oracle Interconnect Stress Test Qualification Specification													X						
Product, Tooling and Factory Qualification	Qual	7093413	Oracle Conductive Anodic Filament (CAF) Resistance Testing Qualification Specification													X						
Product, Tooling and Factory Qualification	Qual	7303358	Laminate Material Qualification – Printed Wiring Boards													X						
Product, Tooling and Factory Qualification	Qual	7300291	Sourcing Engineering: Printed Circuit Board Component Engineering Requirements (CER)													X						
Safety and Regulatory Compliance	Standards	PROC-10085	Agency Standards Reference Guide	X	X	X	X	X	X	X	X	X	X	X	X	X		X	X	X	X	X
Safety and Regulatory Compliance	Audit	7326060	Regulatory Agency Factory Audits – Roles and Responsibilities	X																		X
Safety and Regulatory Compliance	COO	917-1973-xx	Country of Origin Compliance Procedure	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Safety and Regulatory Compliance	COO	PROC-10107	Statement of Origin Form	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Safety and Regulatory Compliance	DG	914-1769-xx	Specification for the Environment - Dangerous Goods	X	X	X	X	X			X							X	X		X	X
Safety and Regulatory Compliance	DG	914-1771-xx	Dangerous Goods Label Placement	X	X	X	X	X			X							X	X	X	X	X
Safety and Regulatory Compliance	DOC	PROC-10084	Major Electronic Component Declaration of Conformity (DOC) Guide	X	X	X	X	X	X	X	X	X	X	X				X	X		X	X
Safety and Regulatory Compliance	DOC	7335087	Commodity Compliance Specification	X	X	X	X	X	X	X	X	X		X				X	X		X	X
Safety and Regulatory Compliance	Compliance	PROC-10103	Product Compliance Traceability Requirements	X	X	X	X	X	X	X	X	X	X	X	X			X	X		X	X
Safety and Regulatory Compliance	Marking	3092	Product Safety Marking and Requirements for Components and Materials	X	X	X	X	X	X	X	X		X		X	X		X	X			X
Safety and Regulatory Compliance	RoHS	914-1742-xx	Environmental Specification - Product Compliance	X	X			X	X						X	X	X	X	X		X	X
Safety and Regulatory Compliance	RoHS	914-1765-xx	Environmental Specification - Declarable and Restricted Materials	X	X	X	X	X	X	X	X			X	X	X	X	X	X		X	X
Safety and Regulatory Compliance	RoHS	990-1237-xx	Restriction of Hazardous Substances (RoHS) Compliance and Declaration Policy	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X		X	X

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Process	Category	Doc. Number	Document Title	A	B	C	D	E	F	G	H	I	J	K	L	M	P	Q	R	S	T	U
Sustaining, Traceability and Corporate Documents																						
Development, Release and Change Controls	AML	923-2349-xx	Sub-Tier Supplier Management Roles and Responsibilities	X	X			X	X									X			X	X
	AML	PROC-10048	AML Status Codes Process Guidelines	X	X	X			X				X	X								X
	PPCN	923-2465-xx	Supply Chain Product and Process Change Notification (PPCN) Request Procedure	X	X	X	X	X	X	X	X		X	X	X	X	X	X	X		X	X
	PPCN	7337335	Create ECR-PQM for PPCN Request	X	X	X	X	X	X	X	X		X	X	X	X	X	X	X		X	X
	Stop Ship	923-1826-xx	Stop Ship and Purge (SSP) Process for Hardware	X	X	X	X	X	X			X			X	X	X	X	X	X	X	X
Process Audits and Quality Management	HDD	7358618	Supplier Engineering Storage Device Manufacturing Requirements for External/Internal Manufacturer (EM/IM) and Joint Design for Manufacturing (JDM)	X	X	X	X															X
	HDD	923-3653-xx	Supply Chain Operations GSM Storage Device Trigger Map							X												
	Memory	923-3522-xx	External Manufacturer (EM) Data Reporting and Support Process Requirements for Memory	X	X										X							X
	Memory	914-1719	Defect Free Quality Agreement (DFQA)												X							
	QMS	923-3415-xx	External Manufacturing – Quality Management Requirements	X	X	X	X															X
	QMS	PROC-10051	External Manufacturing Escalation Requirements	X	X																	X
	RCCA	923-3644-xx	Corrective and Preventive Action Process	X	X	X	X	X	X	X	X		X	X	X	X	X	X	X		X	X
	RCCA	7092240	Storage Device Lead Lot Process							X												
	Quality Reporting	7320588	External Manufacturer (EM) Quality Performance and Failure Data Reporting Process Requirements for Core Mechanical Products	X																		X
	Quality Reporting	7320831	Core Mechanical Supplier Quality Reporting Template	X																		X
	Quality Reporting	7328077	External Manufacturer (EM) Quality Performance and Failure Data Reporting Process Requirements for Core Printed Circuit Board (PCB)	X																		X
	Quality Reporting	7345542	EM Component Quality and Failure Data Requirements	X																		X
	Quality Reporting	ENG-008	Services Repair Data Specification																			X
	Audit	AQP-10025	Supplier Engineering Technical Audit (SETA) form	X																		X
Material Handling	CPUs	912-1696-xx	Packaging CPUs or ASICs for Shipment	X	X																	X
	Returns	917-7040849	In-Line or Field CPU Return Process from External Manufacturer (EM) to Oracle	X																		
	DIMM	923-7042626	DIMM Site Balance and Rework Procedure	X	X				X									X				X
	DIMM	7059302	DIMM Card and Socket Handling and Debug Requirements	X	X																	X
	HDD Packaging	7078198	Storage Device Packaging For Vendor Sale, Site Balance, RMA Transfer, and Return To Vendor (RTV)	X																		
	PSU	914-7344896	Power Supply Handling, Support, Returns and Data Reporting Requirements for External/Internal Manufacturers (EM/IM), PSU Suppliers and Oracle Services	X	X	X		X														X
	NPI	PROC-10094	NPI Obsolete Material Template	X																		X
	Shipping	AQP-10026	Weight Capture Policy for Oracle Finished Goods Fulfillment	X																		X
Product Inspection and Workmanship	VMI	923-2001-xx	Global Cosmetics Quality and Workmanship Standards	X	X	X	X	X	X		X	X	X	X		X		X	X			X
	HDD, VMI	923-3762-xx	GSM External Manufacturer (EM) Visual Mechanical Inspection (VMI) Specification for Hard Disk Drives	X						X												
	PCA/ESD	910-1021-xx	Printed Circuit Board Assembly Workmanship Standards	X	X	X	X	X							X	X		X				X
	PCB	950-1009-xx	Fabrication Specification - Printed Wiring Boards	X	X	X	X	X								X		X				X
	Torque	950-1040-xx	Torque Settings for Use in Assembly of Oracle Products	X				X								X						X
	QC	914-1756-xx	IQC/DTS Minimum Expected Specification	X	X	X										X						X
	Inspection	PROC-10150	Oracle L11 Rack Pre-Shipment Documentation Requirements	X																		X

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Process	Category	Doc. Number	Document Title	Boards, Assemblies & Systems						Drives												
				EM	JDM	ODM	OEM	Power	General	HDD, SDD	OEM Tape	Reman	HBAs, Switches, NICs	Tape Media	Memory	PCB Fab	ASIC / ASSP	Optical/Optoelectronics	Point of Sales/Hospitality	Distributor	Hub	JDM - T1
				Supplier Type Columns																		
				A	B	C	D	E	F	G	H	I	J	K	L	M	P	Q	R	S	T	U
Product Rework And Repair	Reconfig	**923-3671-xx**	Server Rework and Reconfiguration Specifications	X	X	X	X												X			X
	Scrubbing	**923-3723**	System Independent Best Practice for Hard Disk Scrubbing	X	X							X										X
	Disassembly	**914-1760-xx**	SPARC Processors Cleaning Procedure at Disassembly	X	X																	X
	Quality Reporting	**PROC-10060**	FA Manager Tool Use for Failure Analysis	X								X										X
Sustaining, Traceability and Corporate Documents																						
Product Test	HiPot	**923-7024076-xx**	SCO Test: Hipot - Oracle Directed Instrument Settings for Routine Electrical Safety Testing in Production	X	X	X	X	X	X		X	X	X					X	X			X
	ORT	**913-3532-xx**	WWOPS Systems: Ongoing Reliability Test (ORT) Report Template	X	X																	X
	ORT	**913-3549-xx**	WWOPS Systems: Ongoing Reliability Test (ORT) Sizing Template	X																		X
	ORT	**914-1736-xx**	Systems Group Quality: Ongoing Reliability Testing (ORT) Policy	X	X	X	X															X
	Strain, BGA	**914-1739-xx**	Strain Gage Test Procedure	X	X	X	X	X										X				X
Software Download	SWDL	**923-3652-xx**	Software Download (SWDL) Operational Specification	X	X	X																X
Test Code and Test Infrastructure	Infrastructure	**923-3734-xx**	Test Infrastructure Overview	X	X	X																X
Part Numbering and Identification	Host ID	**923-3521-xx**	Host ID Acquisition and Derivation	X	X	X						X										X
	Part No, Rev	**PROC-10050**	Part Number, Revision, and Interchangeability Rules for Orderable and Manufacturing Items	X	X	X	X	X	X		X	X	X	X				X	X			X
	Raw Mat'l	**917-1335-xx**	Specification of Bar-Coded Identification Labels for Packaged Raw and Semi-Finished Materials	X	X	X	X	X	X	X	X	X	X		X	X		X	X			X
	Serial, Lot	**923-3383-xx**	Embedded Logic in Serial Numbers, Lot Codes, and Assembly Identifications (IDs)	X	X	X		X	X			X				X		X	X			X
	Component	**923-2360-xx**	Standard for Component Marking														X					
FRUID	Overview	**950-3757-xx**	Corporate FRU ID: SEEPROM Programing Overview and Procedures for FRU Vendors	X	X	X	X	X										X				X
Product Configuration and Test Data	MFG Records	**PROC-10027**	SCO Product Test: SPEC, TEST BOM Part/Component Content Requirements	X	X	X																X
	MFG Records	**PROC-10041**	L11 Supplier Shop Floor System Data Feed Requirements	X	X																	X
	TDMS	**911-2411-xx**	Oracle Manufacturing Data Transfer Specification	X	X																	X
	TDMS	**PROC-10102**	Oracle Manufacturing Failure Analysis Data Transfer Specification	X	X																	X
	TDMS Tracking	**AQP-10023**	OpenAPI Specification for Real Time Tracking of Product Movement	X	X																	X
	TDMS Environment	**AQP-10024**	OpenAPI Specification for Real Time Environmental Monitoring	X	X																	X
Traceability	MFG Records	**923-3406-xx**	Supplier Traceability Requirements	X	X	X	X	X	X	X		X		X			X	X	X			X
	MFG Records	**7326396**	Supplier Traceability Data, CSV Data Feed Format	X	X	X	X			X		X		X				X				X
	SPARC Records	**923-7052192-xx**	SCO Global Supplier Management: Supplier Traceability Technical Specifications for SPARC CPU Assembly and Test Data Feeds	X		X																
	RFID	**915-2450-xx**	RFID Tag Installation and Traceability	X	X	X	X															X
	RFID	**950-6021**	RFID Tag for Asset Tracking Specification (Global Version)	X	X																	X
Supplier Execution	GSI	**923-3764-xx**	Supplier Specification - Direct Shipment	X	X	X	X	X	X		X	X	X	X				X	X			X

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- E = Power
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- I = Reman
- J = HBAs, Switches, NICs
- K = Tape Media
- L = Memory
- M = PCB Fab
- P = ASIC / ASSP
- Q = Optical/Optoelectronics
- R = Point of Sales/Hospitality
- S = Distributor
- T = Hub
- U = JDM - T1

Security Specifications — NOTE: Government or Industry standards are not supplied by Oracle.

Process: **Security**

Category	Doc. Number	Document Title	A	B	C	D	E	F	G	H	I	J	K	L	M	P	Q	R	S	T	U
HVA	PROC-10090	Physical Security, Control, Traceability and Destruction of Supply Chain High Value Assets at External Manufacturers and Suppliers	X	X	X	X		X	X	X	X	X	X	X	X	X	X	X	X	X	X
RoT	AQP-10027	Handling and Disposition of RoT	X	X	X	X															X
HW Security and Risk Management	PROC-10158	Hardware Security: Managing Supply Chain Risk In Operations	X	X	X	X															X
Information Security	NIST SP 800-137	Information Security Continuous Monitoring (ISCM) for Federal Information Systems and Organizations	X	X	X	X		X				X	X	X	X		X				X
Risk Management	NIST 800-161	Supply Chain Risk Management Practices for Federal Information Systems and Organizations	X	X	X	X	X	X		X		X	X	X	X		X		X		X
Information Security	NIST 800-171	Protecting Controlled Unclassified Information in Nonfederal Systems and Organizations	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Security Controls	NIST 800-53	Security and Privacy Controls for Federal Information Systems and Organizations	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Security Controls	NIST 800-53	Information Security Architecture (PL 8(2)) - Supplier Diversity	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Security Controls	NIST 800-53	System Monitoring (SI-4(17)) - Integrated Situational Awareness	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Security Controls	NIST 800-53	Incident Handling (IR-4(10)) - Supply Chain Coordination	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Risk Management	NIST 800-53	Supply Chain Risk Management (SA-4)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Risk Management	NIST 800-53	Supply Chain Risk Management Plan (PM-31)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Risk Management	NIST 800-53	Risk Assessment (RA)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Protection	NIST 800-53	(SR 7) Supply Chain Operations Security	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Protection	NIST 800-53	(SR 5) Acquisition Strategies, Tools, and Methods	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Protection	NIST 800-53	(SR-5 -1) Acquisition Strategies, Tools, and Methods	Adequate Supply	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Protection	NIST 800-53	(SR-5-2) Acquisition Strategies, Tools, and Methods	Assessments Prior to Selection, Acceptance, Modification, or Update	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Protection	NIST 800-53	Acquisition Process (SA-4)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Protection	NIST 800-53	Customized Development of Critical P0 Components (SA-20)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Protection	NIST 800-53	Physical Access Control (PE-3)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Protection	NIST 800-53	Tamper Resistance and Detection (SA-18, PE-3(5))	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Policy and Procedures SR-1	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Supply Chain Risk Management Plan SR-2	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Supply Chain Risk Management Plan	Establish SCRM Team SR-2(1)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Supply Chain Controls and Processes SR-3	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Supply Chain Controls and Processes	Diverse Supply Base SR-3(1)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Supply Chain Controls and Processes	Limitation of Harm SR-3(2)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Supply Chain Controls and Processes	Sub-tier Flow Down SR-3(3)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Provenance SR-4	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Provenance	Identity SR-4(1)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Provenance	Track and Trace SR-4(2)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Provenance	Validate as Genuine and Not Altered SR-4(3)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Provenance	Supply Chain Integrity — Pedigree SR-4(4)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Acquisition Strategies, Tools, and Methods SR-5	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Acquisition Strategies, Tools, and Methods	Adequate Supply SR-5(1)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Acquisition Strategies, Tools, and Methods	Assessments Prior to Selection, Acceptance, Modification, or Update SR-5(2)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Supplier Assessments and Reviews SR-6	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Supplier Assessments and Reviews	Testing and Analysis SR-6(1)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Supply Chain Risk Assessment	NIST 800-53	Supply Chain Operations Security SR-7	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X

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Process	Category	Doc. Number	Document Title	A	B	C	D	E	F	G	H	I	J	K	L	M	P	Q	R	S	T	U
		NIST 800-53	Notification Agreements SR-8	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
		NIST 800-53	Tamper Resistance and Detection SR-9	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
		NIST 800-53	Tamper Resistance and Detection	Multiple Stages of System Development Life Cycle SR-9(1)	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
		NIST 800-53	Inspection of Systems or Components SR-10	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
		NIST 800-53	Component Authenticity SR-11	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
		NIST 800-53	Component Disposal SR-12	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
Sustaining, Traceability and Corporate Documents																						
Labeling	FG Cartons	950-1419-xx	Specification of Identification Labels for Packaged Finished Goods	X	X	X	X	X	X		X	X	X	X	X			X	X		X	X
	CIS	950-1647-xx	Customer Information Sheet Specification	X	X	X	X		X				X					X				X
	Part Labels	950-4477-xx	Identification, Labeling & Bar-coding Standard for Assemblies	X	X	X	X	X	X		X	X	X		X	X		X			X	X
Sustaining, Traceability and Corporate Documents																						
Packaging	Symbols	412-1186-xx	Package Material Marking Artwork	X	X	X	X	X	X		X	X	X		X	X		X				X
	Pallet	425-1019-xx	Packaging and Palletization Requirements for Inbound/Inter-Plant/Outbound Shipments	X	X	X	X	X	X		X	X	X		X	X		X	X	X	X	X
	Inspection	425-1020-xx	Package Inspection, Regulatory Requirements, and Corrugated Fiberboard Workmanship Standards	X	X	X	X	X	X		X	X	X		X	X		X				X
	OEM	425-1184-xx	Specification for OEM Packaging Development Criteria			X	X	X			X		X	X				X				X
	General	8208016	General Packaging Envelope Mailer Specification	X	X	X	X		X													X
	Supplier Approval	923-7042126	Oracle Approved Manufacturer List (AML) Packaging Supplier Approval Process	X	X																	X
	China RoHS	425-1228-xx	Packaged Product Marking Requirements and Graphics Standards	X	X	X	X	X	X		X	X	X	X	X	X		X	X			X
	ATO Box X of N	425-1237-xx	Packaging Requirements for shipping ATO (Assemble to Order)	X	X	X	X														X	X
	Testing	950-1291-xx	Packaged Product Test Specification	X									X									X
	Taping, Strapping	950-1685-xx	Specification for Materials Used to Close, Seal & Secure Hardware Packaging	X	X	X	X	X	X		X	X	X					X	X		X	X
	Bagging	950-3918-xx	General Bagging Specification	X	X	X	X	X	X		X	X	X	X				X			X	X
	Packing List	PROC-10028	Supply to Oracle Manufacturing - Packing List	X	X	X	X	X	X		X	X	X	X		X	X	X	X	X		X
	Tamper Evident	8218708	Specification for Tamper Evident Packaging	X		X							X		X							X
Paint and Color	Color	950-3302-xx	Product Color Specification	X	X	X	X	X	X		X	X	X					X				X
Industry and Military Standards NOTE: Industry and military standards are not supplied by Oracle.																						
IPC	Quality	IPC-A-610	Acceptability of Electronic Assemblies (and all referenced standards, for example, 600, 7711, 7721, 6011, 6012, 2220, 2221...)	X	X	X	X	X										X	X			X
IPC	Quality	IPC-6011	Generic Performance Specification for Printed Boards													X						
ISO	Quality	ISO 9001:2015	QMS Model for Quality Assurance in Design, Development, Production, Installation and Service	X	X	X	X	X	X	X	X	X	X		X	X		X	X	X	X	X
ASME	Quality	ASME Y14.5-2009	Dimensioning and Tolerancing	X	X	X	X	X	X	X	X	X	X			X	X	X				X
IEC	RoHS	IECQ QC 080000	Electrical & Electronic Components and Products Hazardous Substance Free Standard and Requirements	X	X	X	X	X	X		X	X	X		X	X	X	X	X	X		X
ANSI	ESD	ANSI/ESD S20.20-2021	Protection of Electrical and Electronic Parts, Assemblies and Equipment (Excluding Electrically Initiated Explosive Devices)	X	X	X	X	X	X	X	X				X		X	X	X		X	X
BSI	HiPot	BS EN 50116	Information Technology Equipment - Routine Electrical Safety Testing in Production	X	X														X			X
IPC/JEDEC	Moisture	IPC/JEDEC J-STD-020	Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices	X	X	X	X	X	X		X	X	X	X	X		X	X	X			X
JEDEC	Storage	JEDEC JEP 160	Long-Term Storage for Electronic Solid-State Wafers, Dice and Devices	X																		

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Manufacturing/Operations Requirements Advanced Quality Planning (AQP) Matrix

Document Number: 913-3592	Revision: 91

Determine requirements by selecting the column that best fits commodity or supplier type ▶

Revision: 91

Supplier Type Columns (top headers):

Boards, Assemblies & Systems — EM (A), JDM (B), ODM (C), OEM (D), Power (E); General (F); Drives — HDD, SDD (G), OEM Tape (H); Reman (I); HBAs, Switches, NICs (J); Tape Media (K); Memory (L); PCB Fab (M); ASIC / ASSP (P); Optical/Optoelectronics (Q); Point of Sales/Hospitality (R); Distributor (S); Hub (T); JDM - T1 (U)

Process	Category	Doc. Number	Document Title	A	B	C	D	E	F	G	H	I	J	K	L	M	P	Q	R	S	T	U
			Reference Documents NOTE: Useful for reference but suppliers are not contractually held to the Reference Documents.																			
IPC and JEDEC	Electronic Component and Assembly Standards	IPC-1752	Material Composition Declaration																			
		IPC-7095	Design and Assembly Process Implementation for BGAs																			
		IPC-7351	Generic Requirements for Surface Mount Design and Land Pattern Standard																			
		IPC-7711	Rework of Electronic Assemblies																			
		IPC-7721	Repair and Modification of Printed Boards and Electronic Assemblies																			
		IPC-A-600	Acceptability of Printed Boards																			
		IPC-CM-770	Component Mounting Guidelines for Printed Boards																			
		IPC-SM-840	Qualification and Performance of Permanent Solder Mask																			
		IPC-TM-650	Test Methods Manual																			
		J-STD-001	Requirements for Soldered Electrical and Electronic Assemblies																			
		J-STD-004	Requirements for Soldering Fluxes																			
		J-STD-005	Requirements for Soldering Pastes																			
		J-STD-033	Standard for Handling, Packing, Shipping, and Use of Moisture/Reflow Sensitive Surface Mount Devices																			
		IPC/JEDEC-9704	Printed Wiring Board Strain Gage Test Guideline																			
Product Qualification	Sizing	923-3575-xx	WWOPS Product Lifecycle and Technology: Component Qualification Size Guidelines for Use in Manufacturing																			
	MIL-STD	MIL-HDBK-781A	Reliability Test Methods, Plans, and Environments for Engineering, Development Qualification, and Production Handbook																			
	Telecordia	GR-78	Generic Requirements for the Physical Design and Manufacture of Telecommunications Products and Equipment																			
	Best Practices	923-3695-xx	Systems Quality: Best Practices Guidelines for Manufacturing and Repair Vendors																			
	NCAT Training	-	ExternalMfgNCAT_UserGuide																			
	RCCA	923-3148	Root Cause and Corrective Action (RC/CA) Guidelines for Oracle and Oracle Suppliers																			
	RCCA	7331768	8-D Problem Solving Worksheet																			
Traceability	Quick Start Guide	7079060	Supplier Traceability Data Quick Start Guide																			
IEC	Matl. Declaration	IEC 62474	Material Declaration for Products of and for the Electrotechnical Industry																			

Note: supplier type column O intentionally not used.

Note: supplier type column N has been removed.

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Advanced Quality Planning (AQP) Matrix

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Type Definitions

Matrix Column	Supplier Type		Expanded Name	Supplier Type Definition	Examples Products
A	Boards, Assemblies & Systems	EM	**External Manufacturer of Printed-Circuit Board Assemblies and Systems**	Contract Manufacturer (Oracle classifies these vendors as EM External Manufacturing)– An organization that makes products under a legal agreement with the customer. Contract manufacturers generally serve the Original Equipment Manufacturing (OEM) market.	SPARC, Oracle-designed PCB, SPARC Server
B		JDM	**Joint Design Manufacturer of Printed-Circuit Board Assemblies and Systems**	A Joint Design Manufacturer (JDM) is a balance between OEM and ODM: distinctive parts are designed and manufactured by the outsourcing enterprise, while design and manufacture of certain modules, along with final assembly, are accomplished by the JDM.	SunRay, IO Box
C		ODM	**Original Design Manufacturer of Printed-Circuit Board Assemblies and Systems**	An original design manufacturer (ODM) is a type of contract manufacturer that uses its own designs and intellectual property (IP). The ODM typically owns the IP for the product itself, while the regular contract manufacturer uses its customer's designs and IP.	TBD
D		OEM	**Original Equipment Manufacturer of Printed-Circuit Board Assemblies and Systems**	An organization that sells products made by itself or other organizations under its own name and brand. The OEM usually offers its own warranty, support, and licensing of the product. Oracle buys from OEM's, integrates products and resells as an OEM.	Graphics card, HCA
E	Power		**Supplier of Electrical Power-Conversion Devices**	A supplier of electrical power-conversion devices to Oracle, Oracle's customers or another of Oracle's suppliers.	AC-DC power supply, DC-DC converter
F	General		**General Supplier**	A supplier — of core* material to Oracle, Oracle's customers or another of Oracle's suppliers — that does not fit any other defined category.	monitor, keyboard, mouse, connector, cable, rails, empty rack/chassis, socket, transceiver, ASIC
G	Drives	HDD, SDD	**Supplier of Hard-Disk Drives and Solid State Disk Drives**	A supplier — to Oracle, Oracle's customers or another of Oracle's suppliers — of hard-disk drives and/or solid state disk drives.	HDD, SDD
H		OEM Tape	**Original Equipment Manufacturer's of Magnetic Tape Storage Devices**	A supplier — to Oracle, Oracle's customers or another of Oracle's suppliers — of magnetic tape storage devices of their own design.	LTO tape drive
I	Reman		**Supplier of Re-manufactured Product**	A supplier — to Oracle, Oracle's customers or another of Oracle's suppliers — of re-manufactured Oracle product.	A used, tested and re-packaged, FRU (spare part)
J	HBAs, Switches		**Supplier of Host Bus Adapters, Networking Switches**	A supplier — to Oracle, Oracle's customers or another of Oracle's suppliers — of host-bus adapters or networking switches, being of the suppliers' own design.	HBA, switch
K	Tape Media		**Supplier of Magnetic Tape Media**	A supplier — to Oracle, Oracle's customers or another of Oracle's suppliers — of magnetic tape media.	Enterprise tape media

Matrix Column	Supplier Type	Expanded Name	Supplier Type Definition	Examples Products
L	Memory	Supplier of Solid-state Memory Devices	A supplier — to Oracle, Oracle's customers or another of Oracle's suppliers — of solid-state memory devices.	DDR3 DIMM, USB thumb drive or memory stick, SSD
M	PCB Fab	Supplier of Printed-Circuit Board Fabrications	A supplier — to Oracle, Oracle's customers or another of Oracle's suppliers — of printed circuit board fabrications.	bare printed circuit boards
N	~~Recording Heads/Assemblies~~	Removed	Removed	Removed
P	ASIC/ASSP	Supplier of Application Specific Integrated Circuit /Application Specific Standard Product	A supplier — to Oracle, Oracle's customers or another of Oracle's suppliers — of ASIC/ASSP components	ASIC/ASSP components
Q	Optical/Optoelectronics	Supplier of Optoelectronic products/devices	A supplier — to Oracle, Oracle's customers or another of Oracle's suppliers — of optoelectronic products/devices	Optoelectronic products/devices
R	Point of Sales/Hospitality	Supplier of Point of Sales, Hospitality, Retail, Food & Beverage equipment	Point of Sales/Hospitality - Fulfills OEM products directly to Oracle, Oracle's customers or another of Oracle's suppliers. Typically used in the hospitality and/or retail business unit. Products are sold to Oracle under contract or purchase agreement as a standard 'off the shelf' or slightly modified form.	fiscal printer, battery charger
S	Distributor	Distributor	Distributors buy noncompeting products or product lines, warehouses them, and resells them to retailers or direct to the end users or customers. Oracle typically uses when purchasing conditions are sub-optimal for buying directly from the OEM	off the shelf products including components, boards
T	Hub	Hub Services	Supplier of stocking/warehousing/shipping services to Oracle for Oracle selected and owned material	Specific parts as determined by Oracle
U	JDM - T1	Joint Design Manufacturer-T1 for Printed-Circuit Board Assemblies, Sub-Assemblies, Systems and Racks	A Joint Design Manufacturer - T1 is a collaboration between Oracle, OEM and ODM to deliver rack solutions.	Rack

* Refer to 923-2349 for definitions of core and non-core material.

Note: matrix column O intentionally not used.
Note: supplier type Recording Heads/Assy has been removed.

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Advanced Quality Planning (AQP) Matrix

Document Number: 913-3592	
Revision: 91	

Document History and Approvals

Dash	Rev	Description of Change
	Rev 90	**Added:** 7337335 Create ECR-PQM for PPCN Request **Added X to**: AQP-10027 *Handling and Disposition of RoT* PROC-10158 *Hardware Security: Managing Supply Chain Risk In Operations* NOTE: the changes have been highlighted with blue font on the Matrix tab for ease of use
	Rev 91	**Added:** AQP-10028 *Oracle L11 Functional FAI General Requirements* to supplier type A, EM X to 8218708 *Specification for Tamper Evident Packaging* to supplier type C, ODM NOTE: the changes have been highlighted with blue font on the Matrix tab for ease of use